2SK0662 (2SK662)

Silicon N-channel junction FET

For low-frequency and low-noise amplification

■ Features

- High mutual conductance g_m
- Low noise type
- SMini type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing

■ Package

- Code
  SMini3-G1
- Pin Name
  1: Source
  2: Drain
  3: Gate

■ Marking Symbol: 1O

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Drain-sourse voltage	V_{DS}	30	V
Drain-gate voltage (Source open)	V_{DGO}	30	V
Drain current	I_D	20	mA
Gate current	I_G	10	mA
Power dissipation	P_D	150	mW
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source current *	I_{DSS}	V_{DS} = 10 V, V_{GS} = 0	0.5		12	mA
Gate-source cutoff current	I_{GSS}	V_{GS} = 30 V, V_{DS} = 0			100	nA
Gate-source cutoff voltage	V_{GSC}	V_{DS} = 10 V, I_D = 10 µA	0.1		1.5	V
Mutual conductance	g_{m1}	V_{DS} = 10 V, I_D = 0.5 mA, f = 1 kHz	4			mS
	g_{m2}	V_{DS} = 10 V, V_{GS} = 0, f = 1 kHz	4			
Short-circuit forward transfer capacitance (Common source)	C_{iss}	V_{DS} = 10 V, V_{GS} = 0, f = 1 MHz		14		pF
Reverse transfer capacitance (Common source)	C_{rss}			3.5		pF
Noise voltage	NV	V_{DS} = 30 V, I_D = 1 mA, G_V = 80 dB R_g = 100 kΩ, Function = FLAT		60		mV

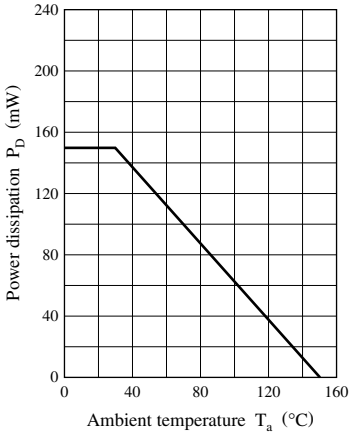
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Rank classification

Rank	P	Q	R
I_{DSS} (mA)	0.5 to 3.0	2.0 to 6.0	4.0 to 12.0

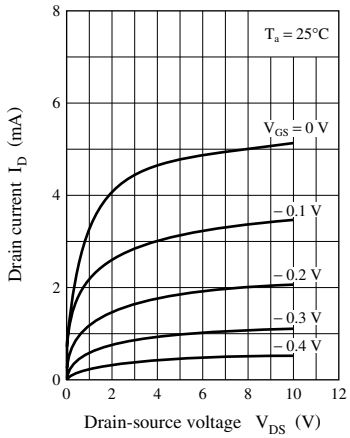
Note) The part number in the parenthesis shows conventional part number.

Maintenance/Discontinued
Planned maintenance type
Planned discontinued type
Please visit following URL about latest information.
http://panasonic.net/sc/e/

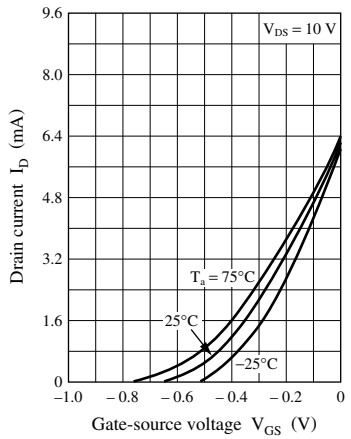
P_D — T_a



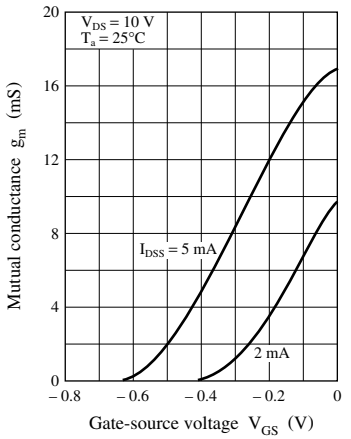
I_D — V_{DS}



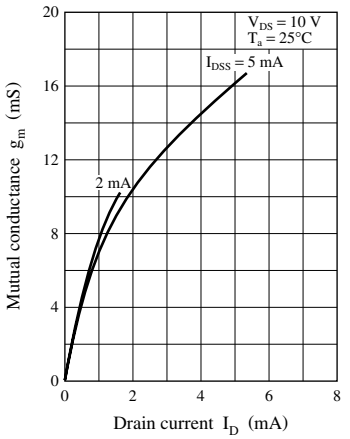
I_D — V_{GS}



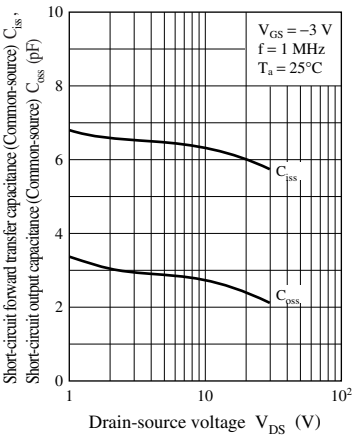
g_m — V_{GS}



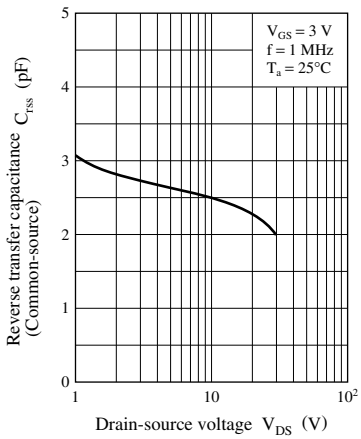
g_m — I_D



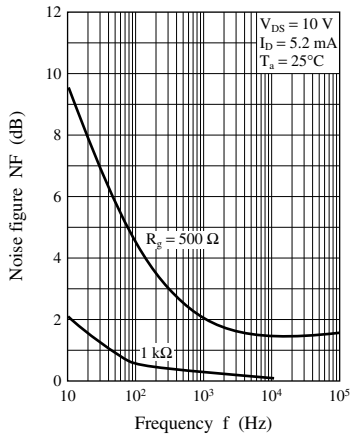
C_{iss} , C_{oss} — V_{DS}



C_{rss} — V_{DS}

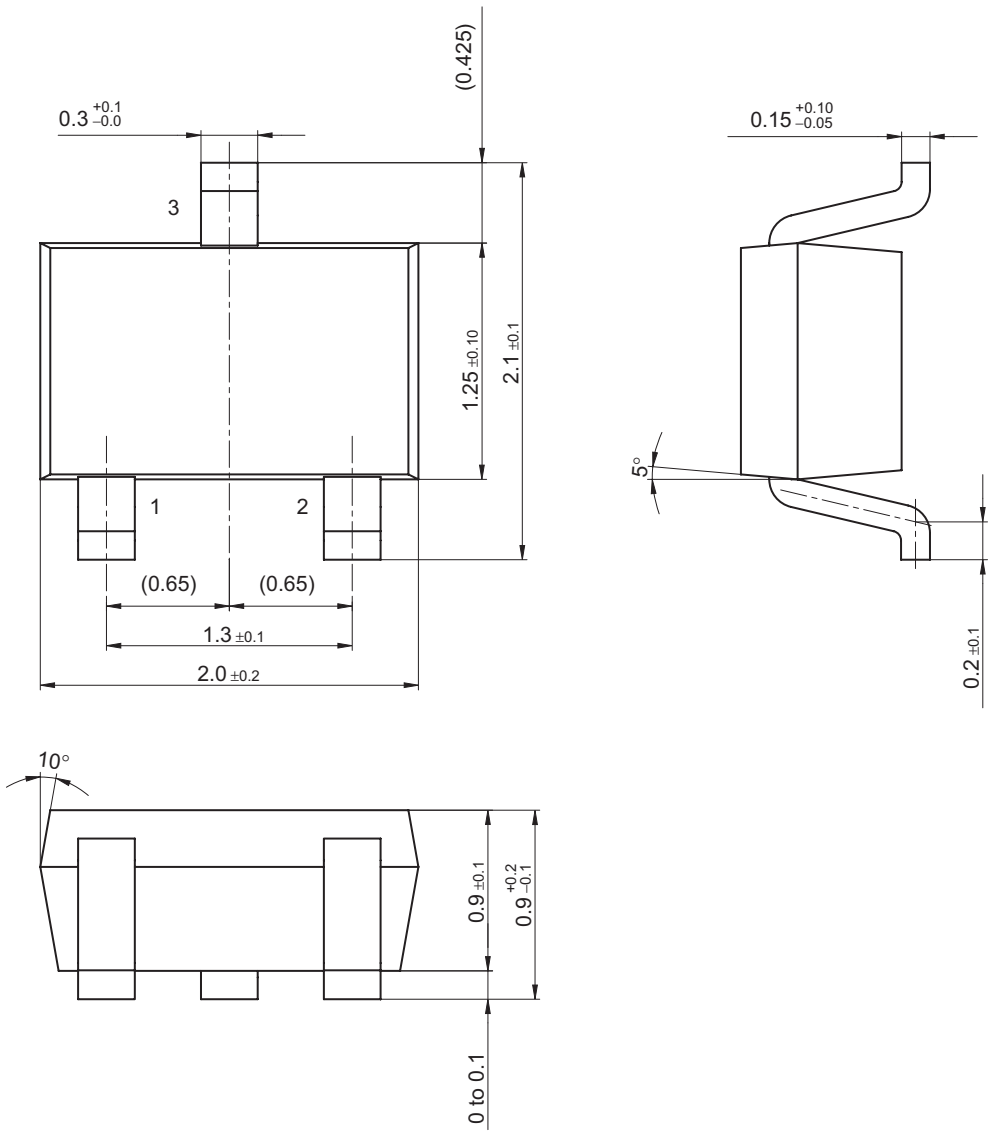


NF — f



SMini3-G1

Unit: mm



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